



SPECIFICATIONS

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High Performance Processor	OUFM D I(FOBSFBFRVFODQQSCPBPTUQDPQD VBEBSFBFBEQPSUDBSUBDIFD VME D QSBIDTBPSBDFMMFOUQSCPBPTUBDIOPMPHOSP BOEQFSBFBEOHOVPSUD	
Memory	TTCUBINDUP(I	
Chipset	Intel® QM87 Chipset providing integrated USB 3.0 and supporting 4th ger Intel® Core™ processor families	neration
Expansion Slot	MMMTFNO1FDPMBDIN Tocpbsetsetmputottopstdpoofduwu[]	
DISPLAY		
GPU	NVIDIA GTX950M	
Display Port	Resolution up to 3840 x 2160@60Hz	
DVI-I	Resolution up to 1920 x 1200@60Hz	
STORAGE		
uSSD	Onboard uSSD SATAIII up to 64 GB	
mSATA	mSATA Solid State Disk (SSD) - up to 512GB Capacity. Rugged Industrial NAND Flash mSATA Storage w/ Rugged -40/+85C High optional Pre-loaded with Linux or Windows OS. 64 / 128 / 256 / 512GB Innodisk 3MG2-P Series MLC SATA III 6Gb/s Flash SS for 520 MB/sec Sequential Read; 350 MB/sec Write Max.	
ETHERNET		
Ethernet	2 x Intel Gigabit Ethernet LAN Interfaces (10/100/1000Mbps)	
REAR I/O		
DisplayPort	2 x 20Pin XTQMBXIPSUconnectors (Female)	
DVI-I	1 x 29Pin DVI-I connector (Female)	
DVI-I Ethernet		
	1 x 29Pin DVI-I connector (Female)	
Ethernet	1 x 29Pin DVI-I connector (Female) 2 x RJ45 Gigabit Ethernet LAN Interfaces	
Ethernet Audio	1 x 29Pin DVI-I connector (Female) 2 x RJ45 Gigabit Ethernet LAN Interfaces 2 x 3.5mm Audio Jacks (1 x MIC, 1 x Line-Out)	
Ethernet Audio Serial Port	1 x 29Pin DVI-I connector (Female) 2 x RJ45 Gigabit Ethernet LAN Interfaces 2 x 3.5mm Audio Jacks (1 x MIC, 1 x Line-Out) 1 x DB9 connector (RS-232/422/485)	
Ethernet Audio Serial Port USB Port	1 x 29Pin DVI-I connector (Female) 2 x RJ45 Gigabit Ethernet LAN Interfaces 2 x 3.5mm Audio Jacks (1 x MIC, 1 x Line-Out) 1 x DB9 connector (RS-232/422/485)	
Ethernet Audio Serial Port USB Port FRONT I/O	1 x 29Pin DVI-I connector (Female) 2 x RJ45 Gigabit Ethernet LAN Interfaces 2 x 3.5mm Audio Jacks (1 x MIC, 1 x Line-Out) 1 x DB9 connector (RS-232/422/485) 2 x USB3.0 standard-A connectors	
Ethernet Audio Serial Port USB Port FRONT I/O Button	1 x 29Pin DVI-I connector (Female) 2 x RJ45 Gigabit Ethernet LAN Interfaces 2 x 3.5mm Audio Jacks (1 x MIC, 1 x Line-Out) 1 x DB9 connector (RS-232/422/485) 2 x USB3.0 standard-A connectors 1 x Power Button	
Ethernet Audio Serial Port USB Port FRONT I/O Button DC-IN	1 x 29Pin DVI-I connector (Female) 2 x RJ45 Gigabit Ethernet LAN Interfaces 2 x 3.5mm Audio Jacks (1 x MIC, 1 x Line-Out) 1 x DB9 connector (RS-232/422/485) 2 x USB3.0 standard-A connectors 1 x Power Button 4P Rugged Terminal connector	





APPLICATIONS, OPER	ATING SYSTEM		
Applications	Commercial and Military Platforms Requiring Compliance to MIL-STD-810G Embedded Computing, Process Control, Intelligent Automation and manufactur-		
	ing applications where Harsh Temperature, Shock, Vibration, Altitude, Dust and EMI Conditions.		
	Used in all aspects of the military.		
0 6	Windows 7, Windows 8, Windows 8.1, Windows 10		
Operating System	Ubuntu13.04, Ubuntu13.10, Ubuntu14.04, Fedora 20		
PHYSICAL			
Dimension (W x D x H)	308 x 149 x 76mm		
Weight	4.3 Kg (9.47 lbs)		
Chassis	Aluminum Alloy, Corrosion Resistant.		
Finish	Anodic aluminum oxide (Color Iron gray)		
Cooling	Natural Passive Convection/Conduction. No Moving Parts.		
-	DC-IN: PHOENIX CONTACT 1776715		
	RJ45 Ethernet: RTB-19GB9J1A		
Connectors	DVI-I : BANGSON DVI02-0123001-T		
	DisplayPort : FOXCONN 3VD21203-H7U0-4		
	Audio: WTJ-035-67S1A01/WTJ-035-67S1A02		
Ingress Protection	Dust Proof (Similar to IP54)		
ENVIRONMENTAL			
	Method 507.5, Procedure II (Temperature & Humidity)		
	Method 516.6 Shock-Procedure V Non-Operating (Mechanical Shock)		
	Method 516.6 Shock-Procedure I Operating (Mechanical Shock)		
	Method 514.6 Vibration Category 24/Non-Operating (Category 20 & 24, Vibration		
AUL CTD 010C T	Method 514.6 Vibration Category 20/Operating (Category 20 & 24, Vibration)		
MIL-STD-810G Test	Method 501.5, Procedure I (Storage/High Temperature)		
	Method 501.5, Procedure II (Operation/High Temperature)		
	Method 502.5, Procedure I (Storage/Low Temperature)		
	Method 502.5, Procedure II (Operation/Low Temperature)		
	Method 503.5, Procedure I (Temperature shock)		
D 1: 1:1:	No Moving Parts; Passive Cooling.		
Reliability	Designed & Manufactured using ISO 9001/2000 Certified uality Program.		
EMC	CE and FCC compliance		
Green Product	RoHS, WEEE compliance		

ORDERING INFORMATION

SR200-SG

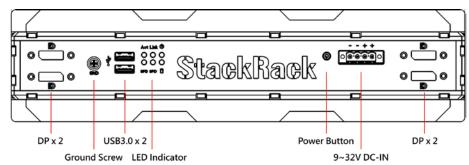
MIL-STD-810G RUGGED COMPUTER WITH INTEL $^{\rm B}$ Core 17-4700EQ, NVIDIA GTX950M GPU, 4 INDEPENDENT DP, MINIPCIE, 9V to 36V DC-IN, EXTENDED TEMP -20 to 60°C

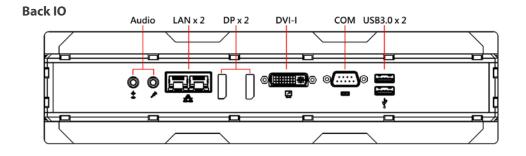


SR200-SG, EBX RUGGED SYSTEM IS A POWERFUL SYSTEM THAT IS DRIVEN BY INTEL® 4TH GENERATION HASWELL CPU AND CHIPSET SOLDERING ONBOARD, INTEGRATED WITH NVIDIA GPU GTX950M THAT SUPPORTS 4 INDEPENDENT DISPLAYPORT. PROCESSOR 17-4700EQ PLUS INTEL® QM87 CHIPSET SUPPORTS CLOCK SPEED 2.4GHz, UP TO 3.4GHz. QUAD CORES, TURBO UP TO 8 CORES TO COPE WITH ENORMOUS DATA COMPUTING.

APPEARANCE

Front IO





DIMENSIONS

